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| QUALIFICATION RESULTS |
| Test | Conditions | Sample Size | Results |
| Solder Heat Resistance(SHR)\* for 8-MINI\_SO | ADI-0049 | **30** | **Pass** |
| Solder Heat Resistance(SHR)\* for 8-LFCSP | ADI-0049 | **30** | **Pass** |
| Latch-Up (8-MINI\_SO) | JEDEC *JESD78* | **6** | **Pass** |
| Electrostatic Discharge*Human Body Model* (8-LFCSP) | ESDA/JEDEC *JDS-001-2011* | **3/voltage** | **Pass 6kV** |
| Electrostatic Discharge*Machine Model* (8-LFCSP) | JEDEC *JESD22-A115* | **3/voltage** | **Pass 200V** |
| Electrostatic Discharge*Field-Induced Charged Device Model* (8-MINI\_SO) | JEDEC *JESD22-C101* | **3/voltage** | **Pass 1.25kV** |
| Electrostatic Discharge*Field-Induced Charged Device Model* (8-LFCSP) | JEDEC *JESD22-C101* | **3/voltage** | **Pass 1.25kV** |

Qualification Plan #9865 – AD8657 Die Revision Ya at TSMC Fab 10 Qualification

\*Preconditioned per JEDEC/IPC J-STD-020